

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7881630

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST
CONVEYING PARTY DATA	
Name	Execution Date
QUIQ CAPITAL, LLC	03/31/2023
RECEIVING PARTY DATA	
Name:	EMBR LABS INC.
Street Address:	24 ROLAND STREET, STE 102
City:	BOSTON
State/Country:	MASSACHUSETTS
Postal Code:	02129
PROPERTY NUMBERS Total: 10	
Property Type	Number
Application Number:	16129182
Application Number:	17109790
Application Number:	62624465
Application Number:	16962322
Application Number:	62791134
Application Number:	17418079
Application Number:	63041724
Application Number:	17221088
Patent Number:	D962929
Application Number:	63041734
CORRESPONDENCE DATA	
Fax Number:	(312)862-2200
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	3128622200
Email:	noreen.gosselin@kirkland.com
Correspondent Name:	NOREEN GOSSELIN
Address Line 1:	KIRKLAND & ELLIS LLP
Address Line 2:	300 NORTH LASALLE
Address Line 4:	CHICAGO, ILLINOIS 60654
ATTORNEY DOCKET NUMBER:	52579-4

NAME OF SUBMITTER:	NOREEN GOSSELIN
SIGNATURE:	/NOREEN GOSSELIN/
DATE SIGNED:	04/03/2023
Total Attachments: 3 source=Quiq Capital Embr Labs IP Security Agreement Termination (Patents)(Executed 3.31.23)_(95362458_2)#page1.tif source=Quiq Capital Embr Labs IP Security Agreement Termination (Patents)(Executed 3.31.23)_(95362458_2)#page2.tif source=Quiq Capital Embr Labs IP Security Agreement Termination (Patents)(Executed 3.31.23)_(95362458_2)#page3.tif	

INTELLECTUAL PROPERTY SECURITY AGREEMENT TERMINATION

(Patents)

THIS INTELLECTUAL PROPERTY SECURITY AGREEMENT TERMINATION is made effective as of March 31, 2023, by and from QUIQ CAPITAL, LLC (the “**Lender**”), under the Loan and Security Agreement, dated as of October 17, 2022, between EMBR LABS INC., a Delaware corporation (the “**Company**”), and the Lender, to the Company as follows:

WHEREAS, the Company and Lender entered into the Intellectual Property Security Agreement, dated as of October 17, 2022 (the “**Intellectual Property Security Agreement**”; capitalized terms used but not defined herein shall have the meanings given them in the Intellectual Property Security Agreement);

WHEREAS, the Intellectual Property Security Agreement was recorded in the United States Patent and Trademark Office on October 21, 2022, at Reel 061500 and Frame 0823 for patents;

WHEREAS, pursuant to the Intellectual Property Security Agreement, the Company granted Lender a security interest in all of the Company’s right, title and interest in, to and under the patents listed on the attached **Exhibit A** (the “**Patents**”) and all patent applications and patent registrations acquired or arising after the date of the Intellectual Property Security Agreement (collectively the “**Intellectual Property**”);

WHEREAS, the Company has satisfied in full the obligations for which the security interest in the Intellectual Property was granted; and


WHEREAS, the Lender wishes to release its security interest in the Intellectual Property;

NOW, THEREFORE, the Lender hereby releases any security interest it may have in the Intellectual Property and all rights to sue for past, present, and future infringements thereof, and retransfers and reassigns to the Company all right, title and interest in the Intellectual Property it may have in and to the foregoing without recourse to the Company. The Lender further agrees, for itself, its successors and assigns, to execute, at the Company’s expense, such further documents, and to perform such further lawful acts, as may reasonably be requested by the Company to effectuate this termination.

[Signature Page Follows]

IN WITNESS WHEREOF the undersigned has executed this Agreement as of the date first written above.

QUIQ CAPITAL, LLC

By: 
Name: Vivek Tiwari
Title: Chief Investment Officer

[Signature Page to Intellectual Property Security Agreement Termination--Patents]

EXHIBIT A

Patents

<u>Description</u>	<u>App/Patent #</u>	<u>File Date</u>
HAPTIC ACTUATORS AND THEIR METHODS OF USE	16/129182	12-Sep-18
HAPTIC ACTUATORS AND THEIR METHODS OF USE	17/109790	2-Dec-20
METHODS AND SYSTEMS FOR DISSIPATING THERMAL LOADS IN WEARABLE DEVICES	62/624465	31-Jan-18
METHODS AND SYSTEMS FOR DISSIPATING THERMAL LOADS IN WEARABLE DEVICES	16/962322	15-Jul-20
THERMAL AND VIBROTACTILE HAPTIC ACTUATORS	62/791134	11-Jan-19
THERMAL AND VIBROTACTILE HAPTIC ACTUATORS	17/418079	24-Jun-21
LOW POWER THERMOELECTRIC SYSTEMS	63/041724	19-Jun-20
LOW POWER THERMOELECTRIC SYSTEMS	17/221088	2-Apr-21
WEARABLE DEVICE	D962929	3-Apr-20
THERMALLY CONTROLLED FACE ENGAGING DEVICE	63/041734	19-Jun-20